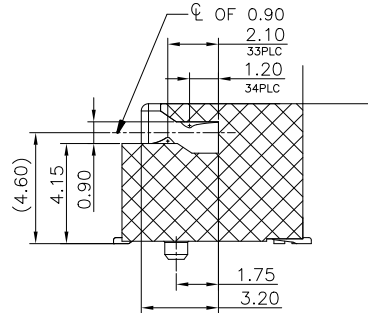
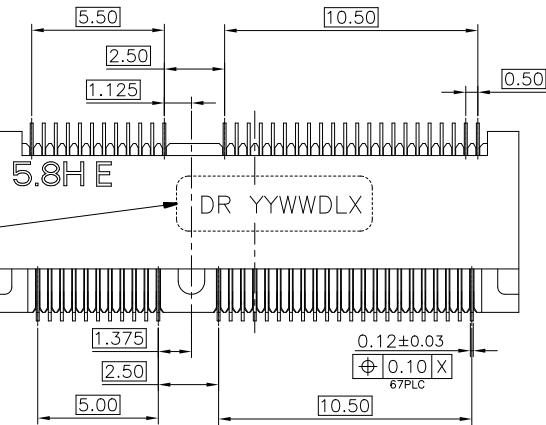


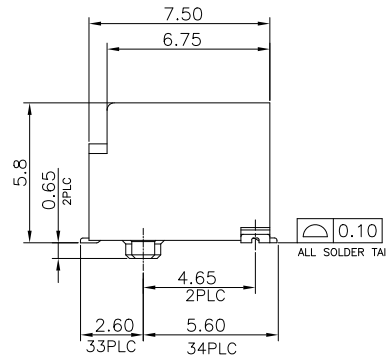
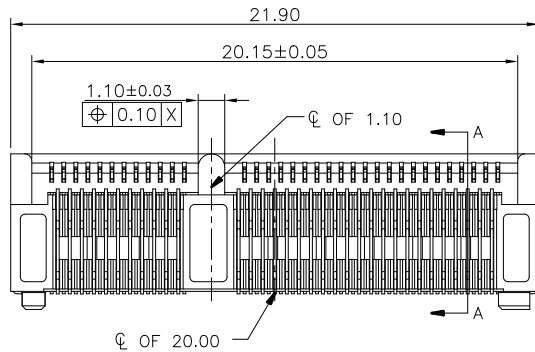
HF

Halogen Free

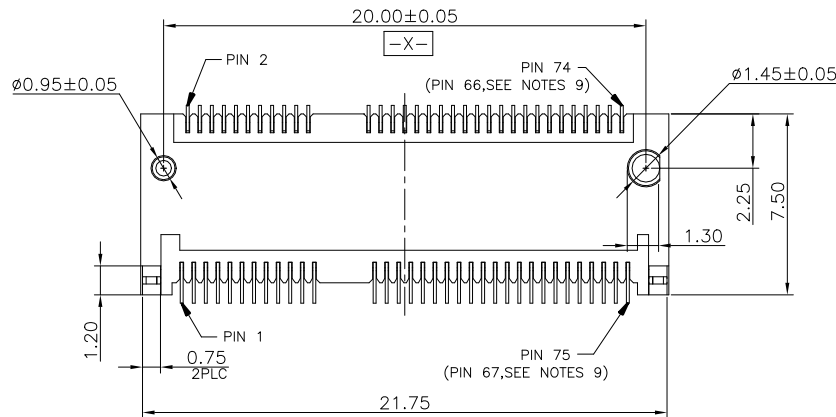
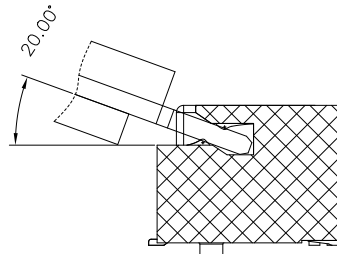
LOGO&DATE CODE
SEE NOTES 3



SECTION: A-A
SCALE: 1:1



MATING ANGLE ILLUSTRATION



REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A			INITIAL RELEASE	2024.02.04	Sid Guo

NOTES:
PRODUCT MUST MEETS CONTROLLED SUBSTANCES SPEC. ROHS 2.0
AND MEET DEREN CONTROLLED SUBSTANCES SPEC PER WI-PB-S-010

1.MATERIAL:

- 1.1 HOUSING:LCP, UL94V.0; COLOR: BLACK
- 1.2 CONTACT PHOSPHOR BROZNE.
- 1.3 SOLDER PEG AND LATCH:STAINLESS STEEL.

2.FINISH:

- 2.1 CONTACT: 50u" MIN NICKEL UNDERPLATED ALL OVER.
GOLD FLASH PLATING ON SOLDERTAIL.
GOLD PLATING (SEE NOTE 9) ON CONTACT AREA.
- 2.2 SOLDER PEG:
MATTE TIN 100u" MIN. AND NICKEL 50u" MIN UNDERPLATED.

3.LOGO&DATE CODE:

- LOGO: DR OR DEREN
DATECODE: YYWDLX
YY: YEAR (09: 2009)
WW: WEEK (25: THE 25TH WEEK)
D: DAY (1~7: SUNDAY~SATURDAY)
L: LINE NUMBER OF ASSEMBLY (A: LINE A)
X: MANUFACTURE CODE

4.REFLOW SOLDER CAPABLE TO 260°C 10 SEC.

5.ELECTRICAL CHARACTERISTICS :

- 5.1 CURRENT RATING:0.5AMP.
- 5.2 CONTACT RESISTANCE:55 MILLIOHMS MAX. INITIAL,
20 MILLIOHMS MAX. CHANGE AFTER TEST.
- 5.3 IMPEDANCE:85±10% OHMS
- 5.4 INSULATION RESISTANCE:500 MEGOHMS MIN. INITIAL
100 OHM MIN. CHANGE AFTER TEST.
- 5.5 DIELECTRICAL WITHSTAND VOLTAGE:300V AC
MIN.AT SEA LEVEL.

6.MECHANICAL CHARACTERISTICS:

- 6.1 INSERTION FORCE:20N MAX.PER CONTACT PAIR.
- 6.2 DURABILITY:60 MATING AND UNMATING CYCLES.
- 6.3 CONTACT RETENTION FORCE:0.1Kgf

7.ENVIRONMENTAL CHARACTERISTICS:

OPERATING TEMPERATURE RANGE:40°C TO +80°C.

8.RECOMENDED STENCIL THICKNESS:0.12MM MIN.

9.CONNECTOR ACTUAL PIN QUANTITY IS 67,AS THE KEY TAKING OUT 8 PINS.

10.PART NUMBER DESCRIPTION:

5621D3-038 H X 4 1 1 X

PACKING CODE:

- R: EMBOSS WIDTH 44mm, SLOT BACKWARD
2: EMBOSS WIDTH 32mm, SLOT FORWARD

Logo:

- 0:No Logo
1:DR Logo

Color:

- 1:Black
2:White

KEY TYPE:

- 4: KEY E

PLATING CODE:

- 1: AuGF 2: Au5u"
3: Au10u" 4: Au15u"
5: Au30u"

HALOGEN CODE:

- H:HALOGEN FREE



DEREN

SHENZHEN DEREN ELECTRONIC CO., LTD

DIM	TOL	DIM	TOL
x.	±0.30	x.	±2°
.x	±0.25	.x	±1°
.xx	±0.15		

DRAW NO.
SC2309641-2

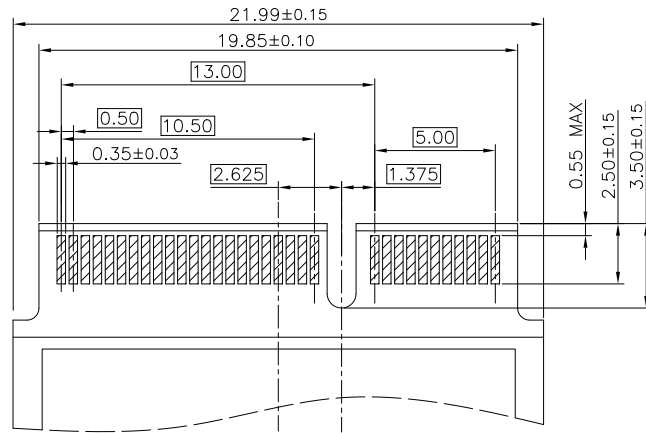
REV. A

C-DWG:	TY	DATE	TITLE: NGFF 5.8H KEY E GEN4
DESIGN:	Sid Guo	2024.02.04	P/N: 5621D3-038HX411X
CHECK:	Mike Chen	2024.02.04	SHEET: 1/4
APPROVAL:	Bill Lin	2024.02.04	SCALE: N/A UNIT: mm

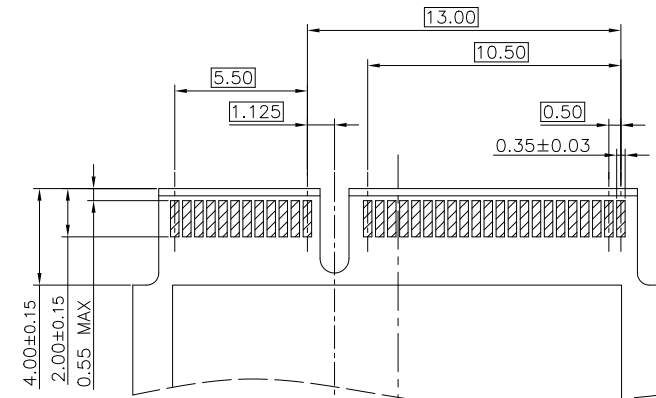
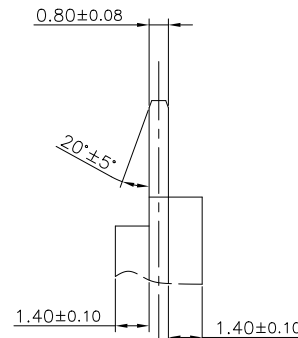
HF

Halogen Free

PLUG PCB

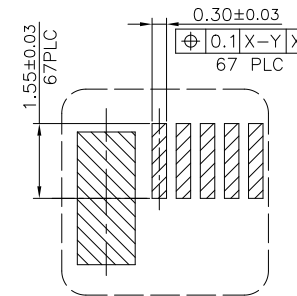
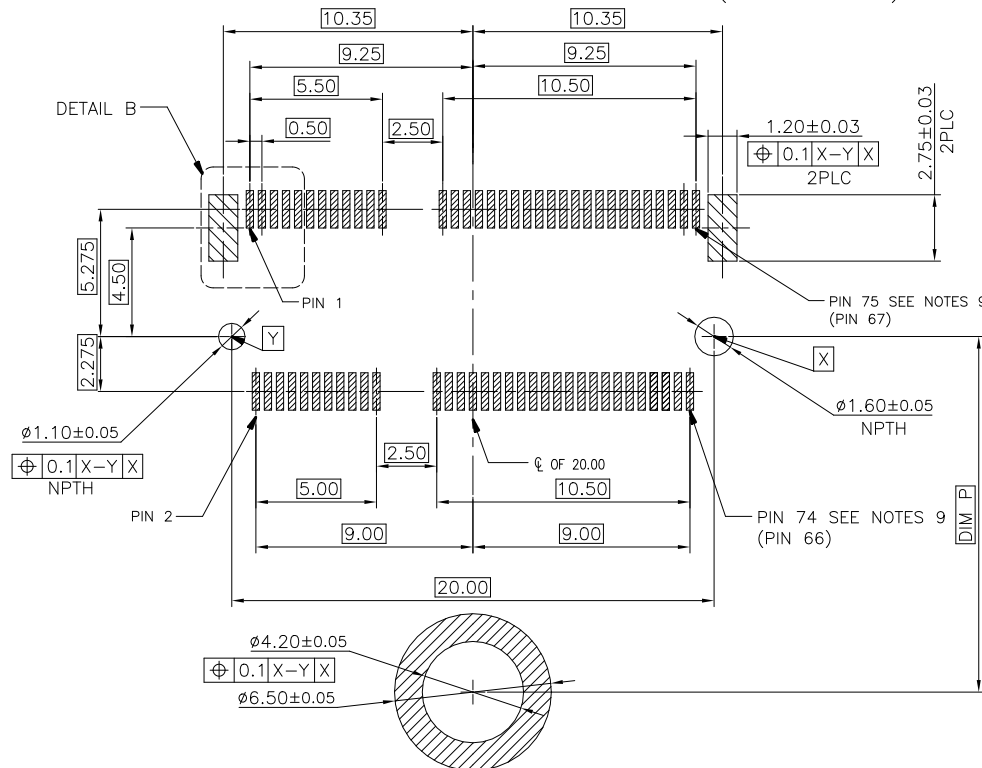


BOTTOM SIDE



TOP SIDE

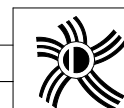
RECOMMENDED PCB LAYOUT(TOP VIEW)



DETAIL B
SCALE 2:1

22110	108.25
2280	78.25
2260	58.25
2242	40.25
2230	28.25
3042	40.25
3030	28.25
MODULE TYPE	DIM P

DIM	TOL	DIM	TOL
.x.	±0.20	.x.	±2°
.x	±0.10	.x	±1°
.xx	±0.05		



DEREN
SHENZHEN DEREN ELECTRONIC CO., LTD

DRAW NO.
SC2309641-2

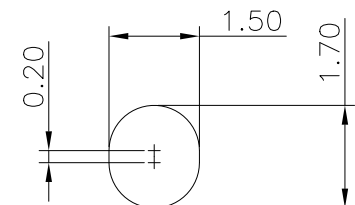
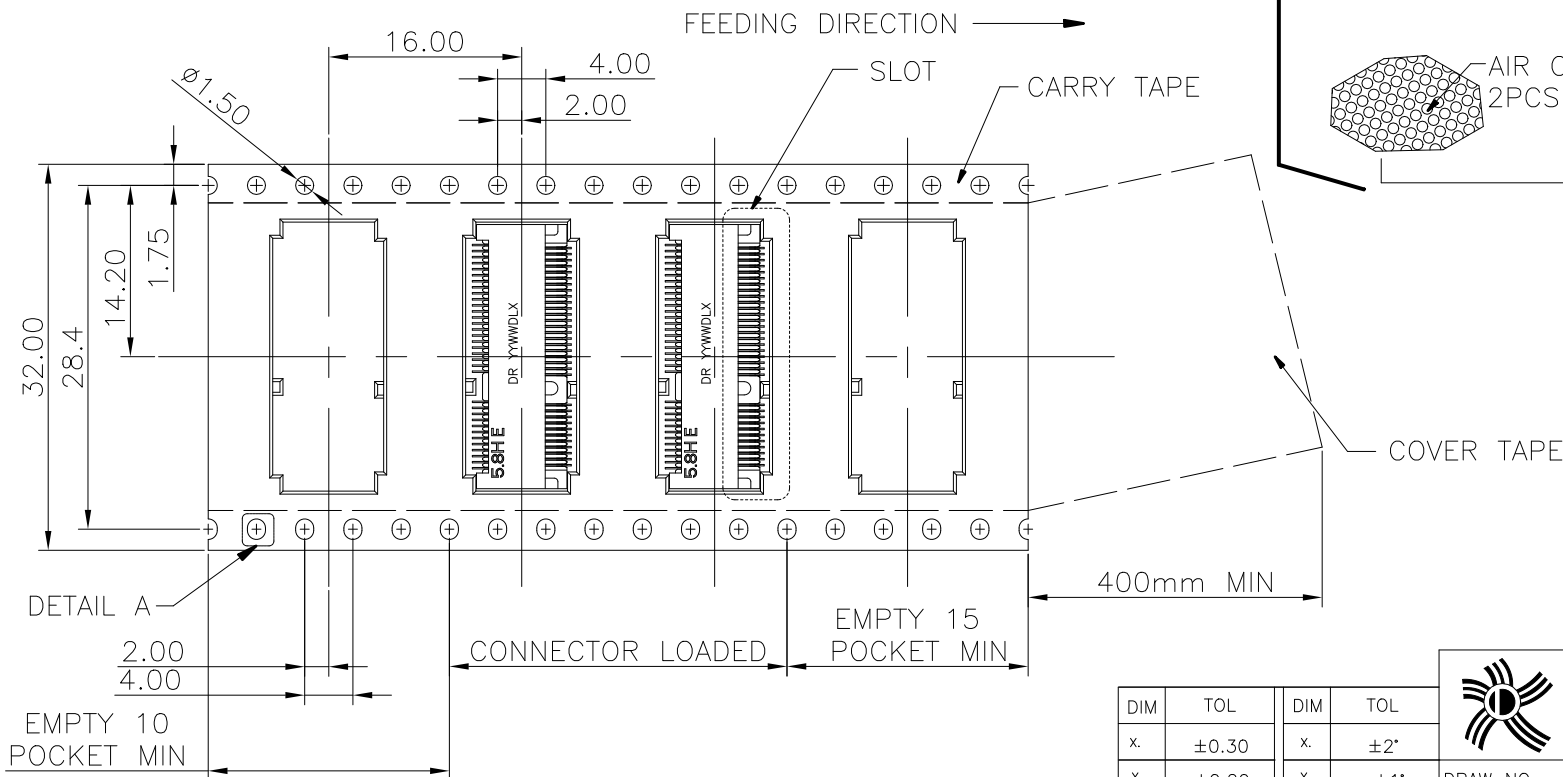
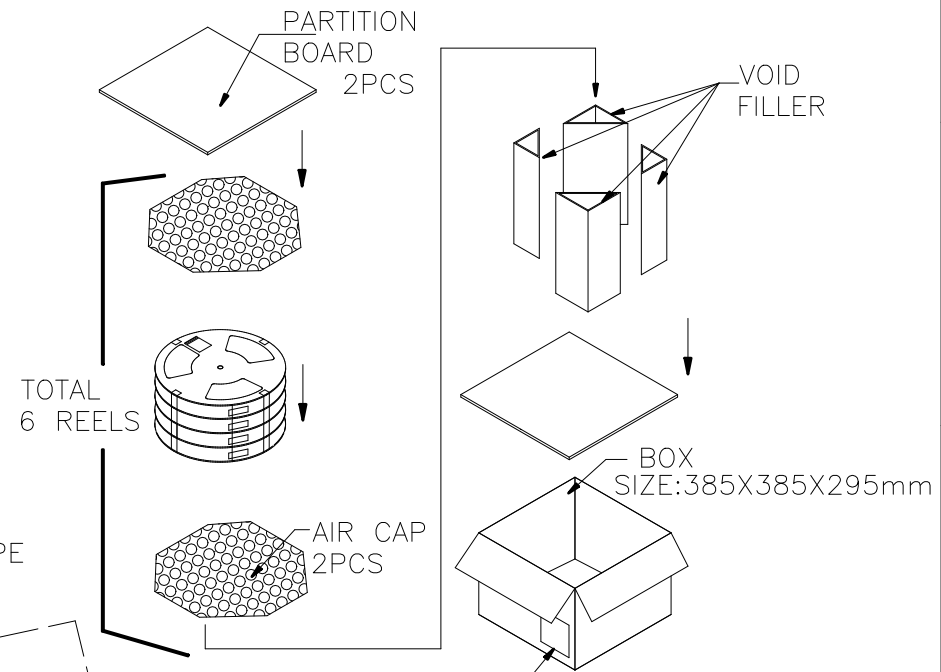
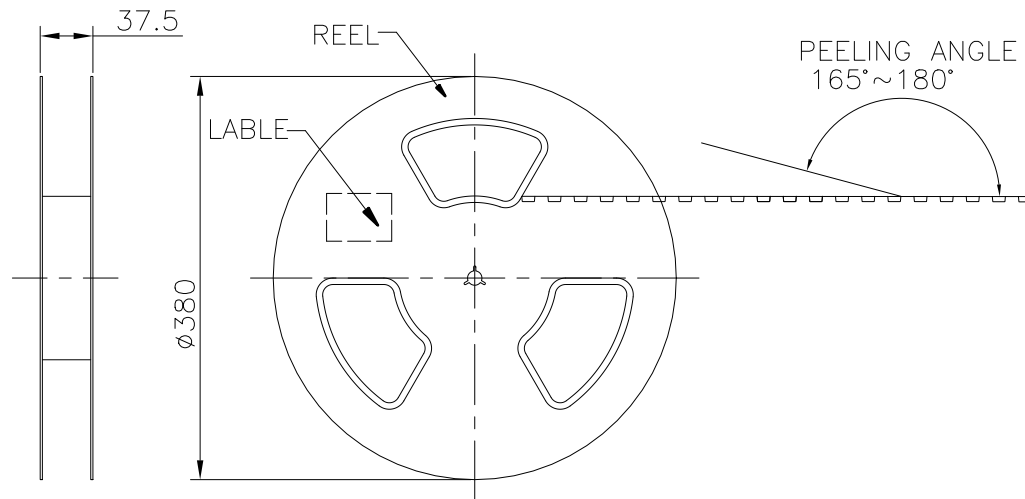
C-DWG:	TY	DATE
DESIGN:	Sid Guo	2024.02.04
CHECK:	Mike Chen	2024.02.04
APPROVAL:	Bill Lin	2024.02.04

TITLE: NGFF 5.8H KEY E GEN4
P/N: 5621D3-038HX411X
SHEET: 2/4
SCALE: N/A
UNIT: mm

HF

Halogen Free

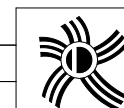
5621D3-038HX4112 EMBOSS WIDTH 32mm, SLOT FORWARD



DETAIL A
SCALE: 5:1

800	6	4800
PCS/REEL	REELS/BOX	PCS/BOX

DIM	TOL	DIM	TOL
x.	±0.30	x.	±2°
.x	±0.20	.x	±1°
.xx	±0.15		



DEREN

SHENZHEN DEREN ELECTRONIC CO., LTD

DRAW NO.
SC2309641-2

DESIGN: Sid Guo

2024.02.04

CHECK: Mike Chen

2024.02.04

APPROVAL: Bill Lin

2024.02.04

TITLE: NGFF 5.8H KEY E GEN4

P/N: 5621D3-038HX411X

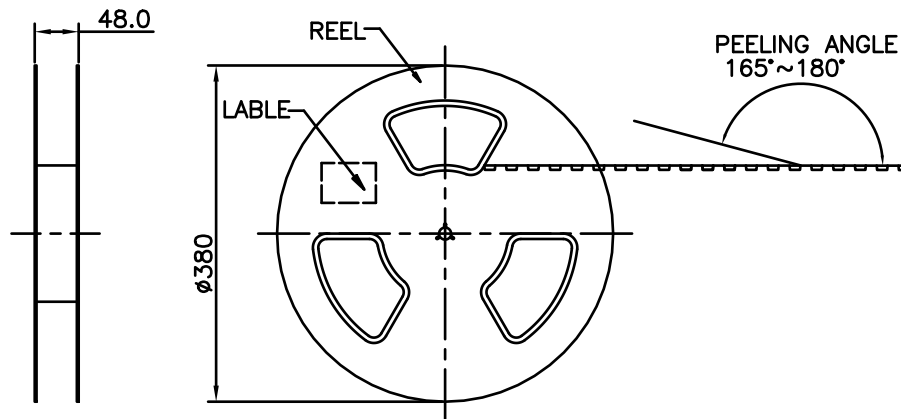
SHEET: 3/4

SCALE: N/A UNIT: mm

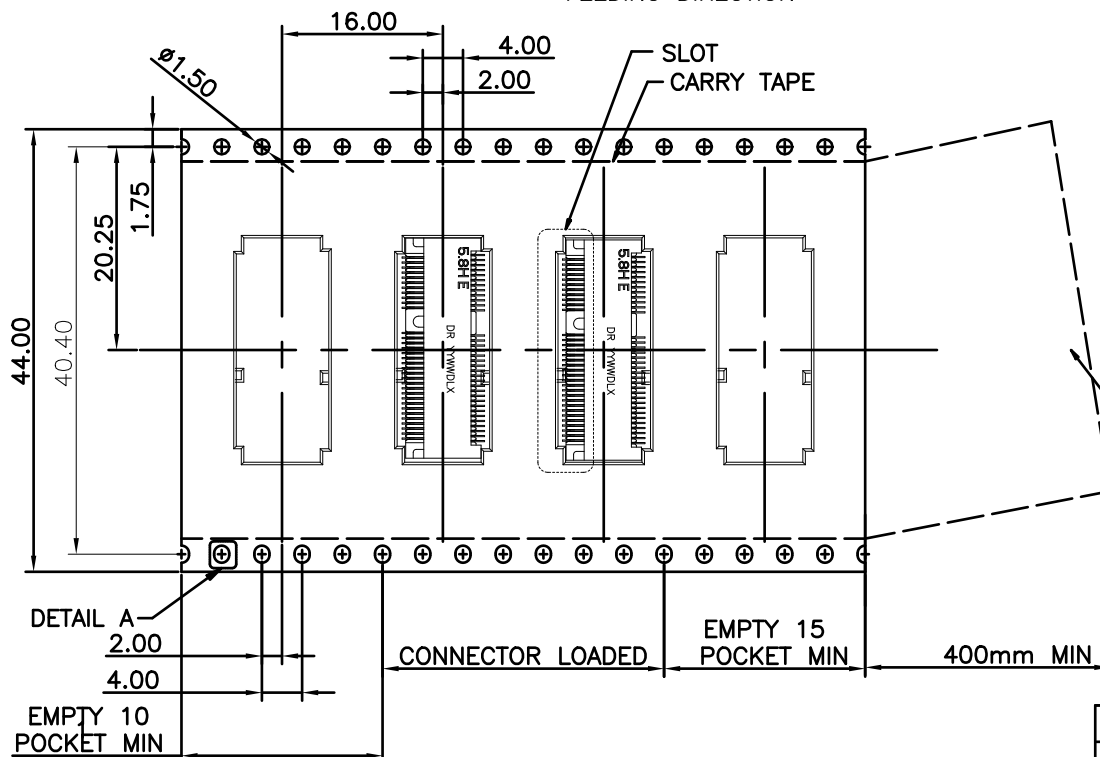
HF

Halogen Free

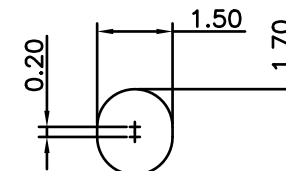
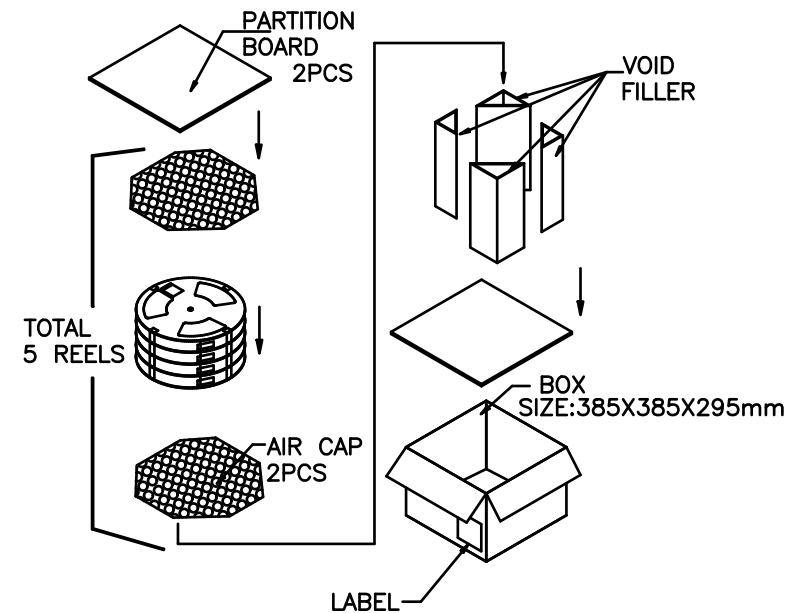
5621D3-038HX411R EMBOSS WIDTH 44mm, SLOT BACKWARD



FEEDING DIRECTION →



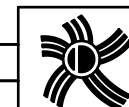
COVER TAPE



DETAIL A
SCALE: 5:1

800	5	4000
PCS/ REEL	REELS/ BOX	PCS/BOX

DIM	TOL	DIM	TOL
x	±0.30	x	±2°
.x	±0.20	.x	±1°
.xx	±0.15		



DEREN
SHENZHEN DEREN ELECTRONIC CO., LTD

DRAW NO.
SC2309641-2

REV. A

C—DWG:	TY	DATE
DESIGN:	Sid Guo	2024.02.04
CHECK:	Mike Chen	2024.02.04
APPROVAL:	Bill Lin	2024.02.04

TITLE: NGFF 5.8H KEY E GEN4

P/N: 5621D3-038HX411X

SHEET:	4/4	
SCALE:	N/A	UNIT: mm